

WHAT IS CLAIMED IS:

1. A microactuator device having a cut face formed by cutting, wherein said cut face is subjected to anti-release treatment for preventing release of particles produced by cutting.

2. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by baking an entire surface of said microactuator device including said cut face to form a sintered surface after cutting into a final product shape.

3. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by polishing an entire surface of said microactuator device including said cut face formed by cutting after baking.

4. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by reheating an entire surface of said microactuator device including said cut face formed by cutting after baking to thereby refix said particles to said entire surface.

5. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by exclusively heating said cut face formed by cutting after baking to thereby refix said particles to said cut face.

6. A microactuator device according to any one of claims 2 through 5, wherein said anti-release treatment is followed by washing of an entire surface of said microactuator device including said cut face to remove said particles.

7. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by coating said cut face formed by cutting after baking with a glass to avoid exposure of said cut face.

8. A microactuator device according to claim 1, wherein said anti-release treatment is carried out by coating an entire surface of said microactuator device including said cut face formed by cutting after baking with

a flexible resin material which hardly suppresses the displacement of said microactuator device.

9. A microactuator device according to any one of claims 1 through 8, wherein said microactuator device comprising a multilayer structure which includes a plurality of piezoelectric elements and a plurality of internal electrodes alternately laminated and which has said cut face.

10. A head supporting arrangement comprising:
a base plate to be fixed;
a support spring for supporting a head; and
a microactuator device connected to said base plate and said support spring, said microactuator device being coated with a coating film collectively with portions of said base plate and said support spring which are adjacent to said microactuator device.

11. A head supporting arrangement comprising:
a base plate to be fixed;
a support spring for supporting a head; and
a plurality of microactuator devices connected between said base plate and said support spring, said microactuator devices being collectively covered with a coating film.

12. A head supporting arrangement according to claim 11, further comprising a flexible substrate receiving said microactuator devices mounted thereon and connected between said base plate and said support spring, said flexible substrate being coated with said coating film together with said microactuator devices.

13. A head supporting arrangement according to any one of claims 10 through 12, wherein said support spring is elastically coupled with said base plate.

the head supporting arrangement according to any one of claims 10 through 13; and

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